

## 1. General description

Ultrafast power diode in TO-263 (D2PAK) plastic package.

## 2. Features and benefits

- Low on-state loss
- Low leakage current
- Soft reverse recovery characteristics
- High thermal cycling performance

## 3. Applications

- Home appliance power supply
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

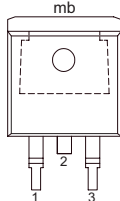

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V <sub>RRM</sub>	repetitive peak reverse voltage		600				V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 128 °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	15				A
I <sub>FRM</sub>	repetitive peak forward current	δ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 128 °C; square-wave pulse	30				A
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse; <a href="#">Fig. 4</a>	150				A
		t <sub>p</sub> = 8.3 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse;	165				A
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.1	1.38	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 125 °C; <a href="#">Fig. 6</a>		-	0.96	1.25	V
Dynamic characteristics							
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	50	60	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	no connected		
2	K	cathode[1]		
3	A	anode		
mb	mb	mounting base; connected to cathod		

[1] It is not possible to connect to pin 2 of the TO-263 package.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYT79B-600P	TO-263	plastic single-ended surface-mounted package (D2PAK); 3-leads (one lead cropped)	D2PAK

## 7. Marking

Table 4. Marking codes

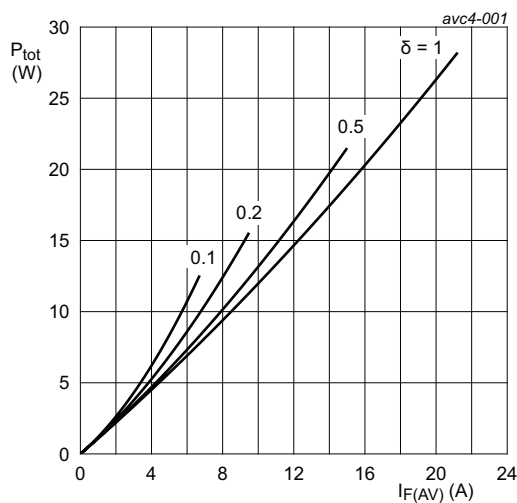
Type number	Marking codes
BYT79B-600P	BYT79B-600P

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

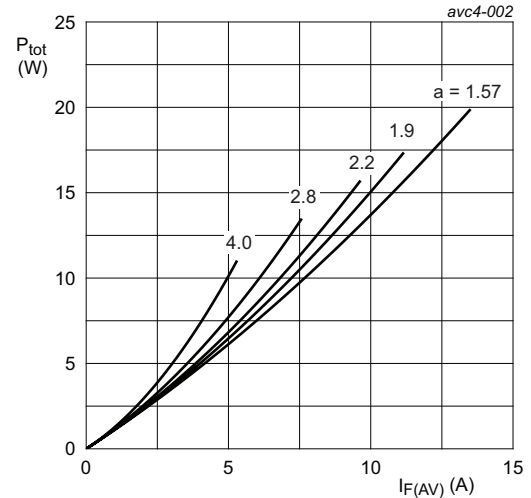
Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		600	V
$V_{RWM}$	crest working reverse voltage		600	V
$V_R$	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 128^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	15	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_{mb} \leq 128^\circ\text{C}$ ; square-wave pulse	30	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\ \text{ms}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	150	A
		$t_p = 8.3\ \text{ms}$ ; $T_{j(\text{init})} = 25^\circ\text{C}$ ; sine-wave pulse;	165	A
$T_{stg}$	storage temperature		-65 to 175	$^\circ\text{C}$
$T_j$	junction temperature		175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.080\ \text{V}; R_s = 0.0118\ \Omega$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 1.080\ \text{V}; R_s = 0.0118\ \Omega$$

**Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**

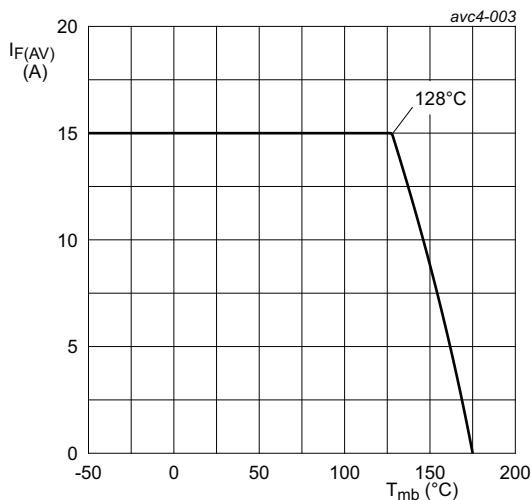


Fig. 3. Forward current as a function of mounting base temperature; maximum values

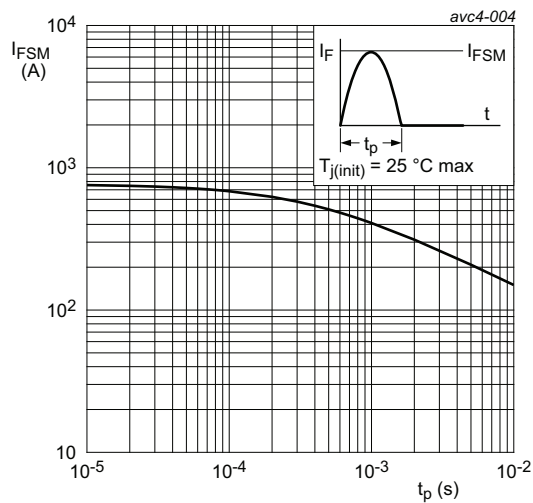


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>		-	-	2.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	50	-	K/W

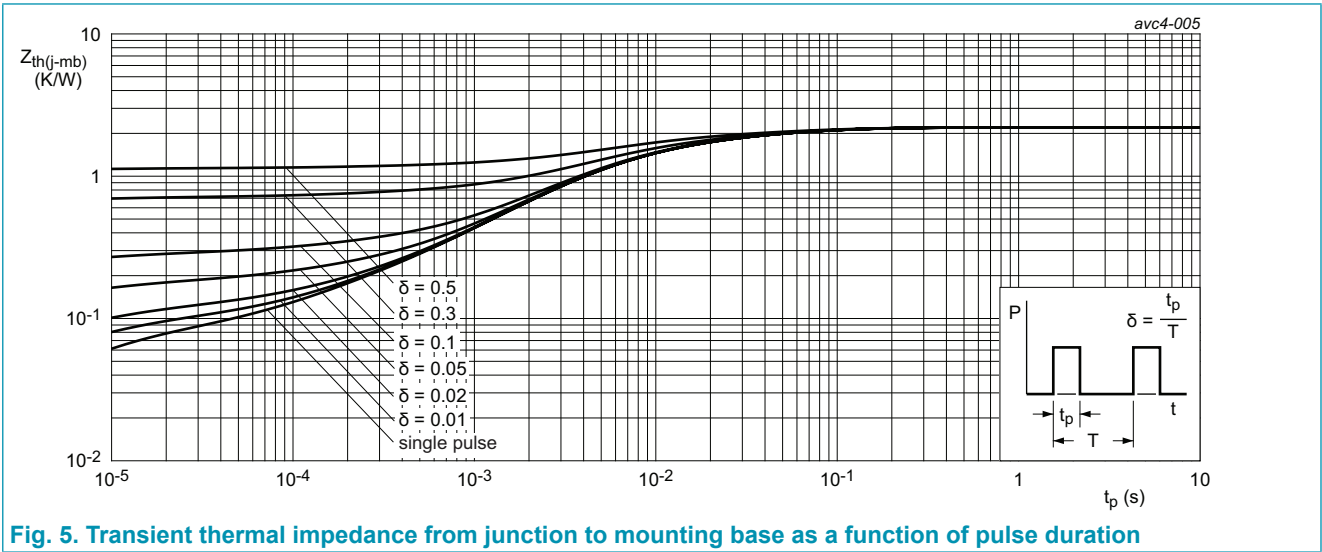
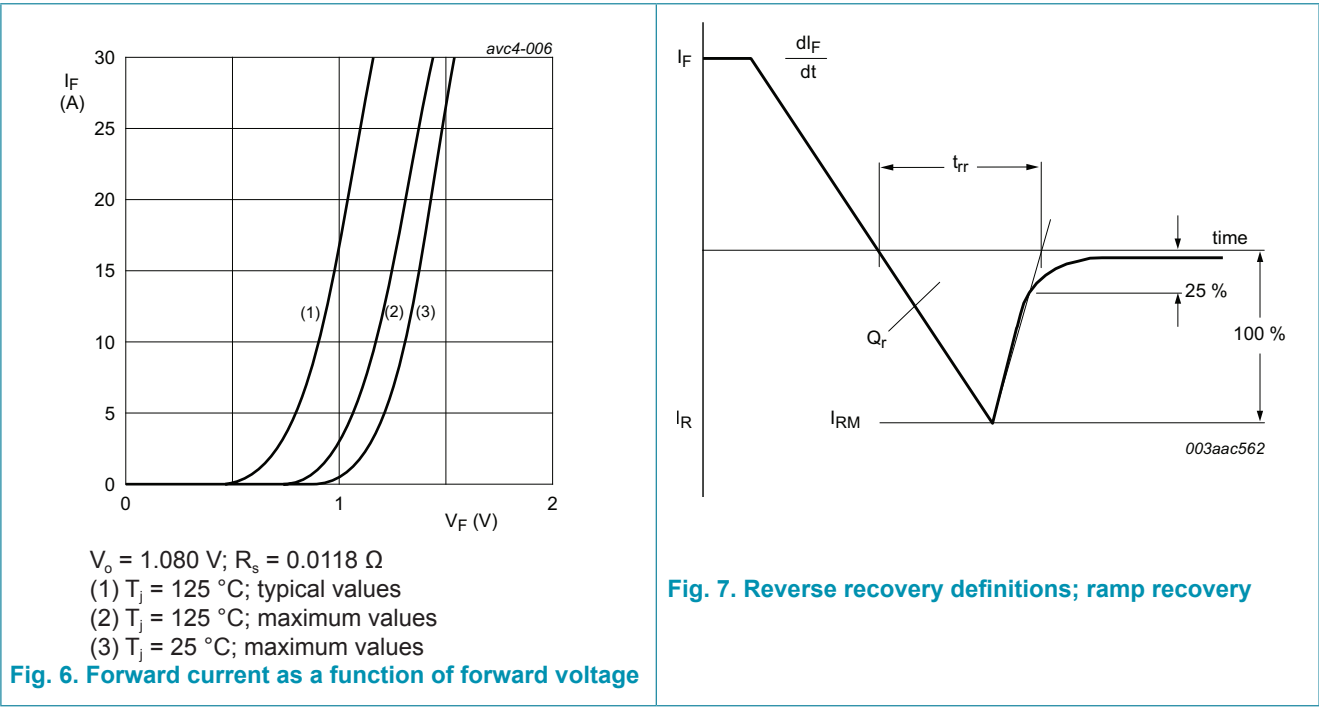


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

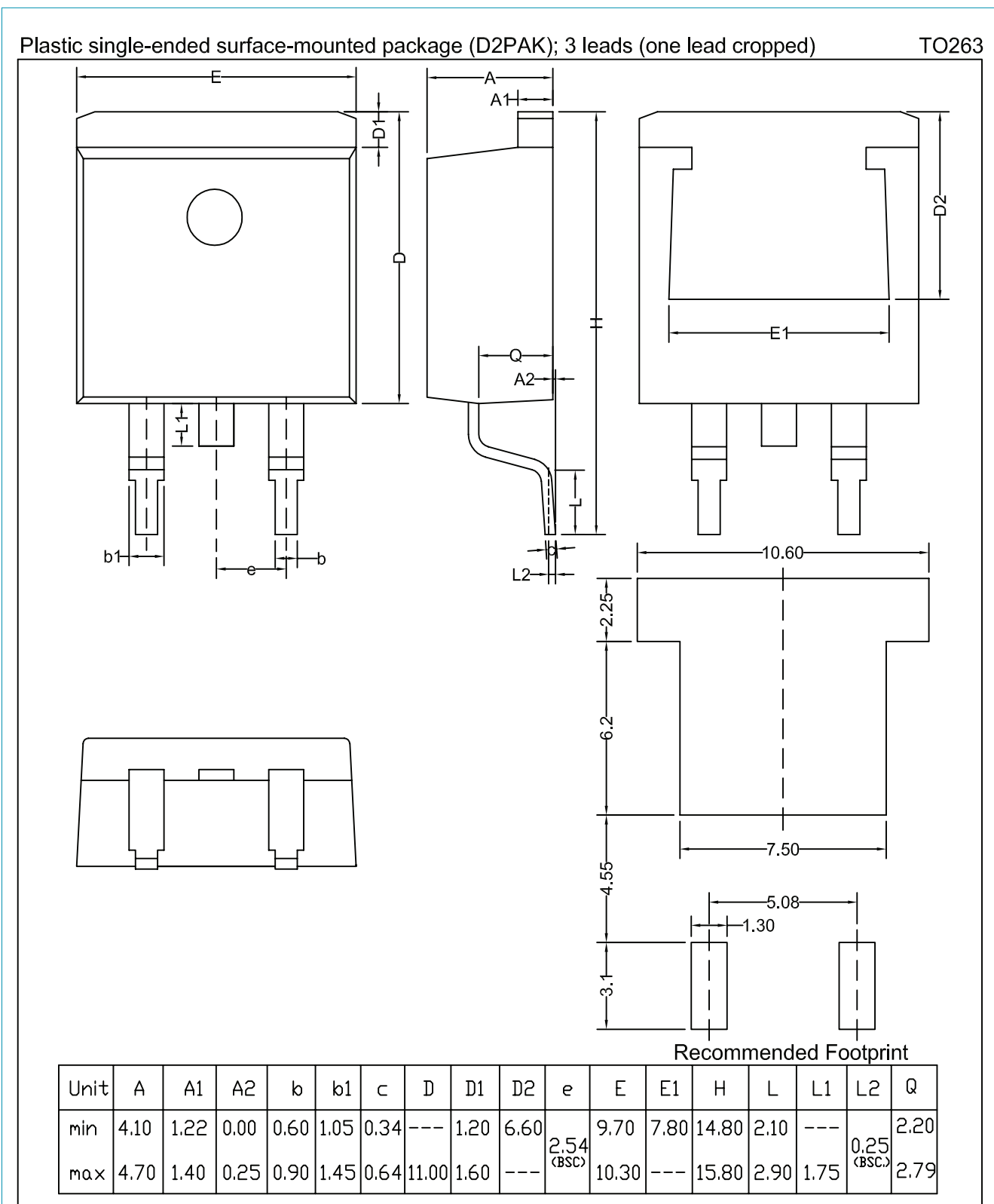
10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward current	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.1	1.38	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 125 °C; <a href="#">Fig. 6</a>		-	0.96	1.25	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	1	10	μA
		V <sub>R</sub> = 600 V; T <sub>j</sub> = 125 °C		-	80	200	μA
Dynamic characteristics							
I <sub>RM</sub>	peak reverse recovery current	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	3	-	A
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	50	60	ns
Q <sub>r</sub>	reverse charge	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	60	-	nC
		I <sub>F</sub> = 2 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 20 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	60	110	nC



11. Package outline



## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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